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April 2015

FDD5353

N-Channel Power Trench[®] MOSFET 60V, 50A, 12.3m Ω

Features

- Max $r_{DS(on)} = 12.3 m\Omega$ at $V_{GS} = 10 V$, $I_D = 10.7 A$
- Max $r_{DS(on)} = 15.4 \text{m}\Omega$ at $V_{GS} = 4.5 \text{V}$, $I_D = 9.5 \text{A}$
- 100% UIL Tested
- RoHS Compliant

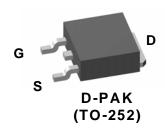


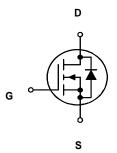
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Application

- Inverter
- Synchronous rectifier
- Primary switch





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			60	V
V _{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	$T_C = 25^{\circ}C$		50	
I _D	-Continuous	T _A = 25°C	(Note 1a)	11.5	Α
	-Pulsed			100	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	253	mJ
D	Power Dissipation	$T_C = 25^{\circ}C$		69	W
P_D	Power Dissipation	T _A = 25°C	(Note 1a)	3.1	VV
T _{.I} , T _{STG}	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	40	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD5353	FDD5353	D-PAK (TO-252)	13"	16mm	2500 units

Electrical Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, referenced to 25°C		77		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 48V,$			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250μA, referenced to 25°C		-8		mV/°C
	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 10.7A$		10.1	12.3	
r _{DS(on)}		$V_{GS} = 4.5V, I_D = 9.5A$		12.1	15.4	mΩ
		$V_{GS} = 10V, I_D = 10.7A, T_J = 125^{\circ}C$		16.7	20.3	
9 _{FS}	Forward Transconductance	$V_{DD} = 5V, I_D = 10.7A$		41		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 30V, V _{GS} = 0V, f = 1MHz	2420	3215	pF
C _{oss}	Output Capacitance		215	285	pF
C _{rss}	Reverse Transfer Capacitance		120	180	pF
R_g	Gate Resistance	f = 1MHz	1.7		Ω

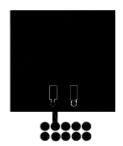
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		11	20	ns
t _r	Rise Time	$V_{DD} = 30V, I_D = 10.7A,$	6	11	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GEN} = 6\Omega$	36	58	ns
t _f	Fall Time		4	10	ns
Qg	Total Gate Charge	V _{GS} = 0V to 10V	46	65	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } 4.5V$ $V_{DD} = 30V,$ $I_{D} = 10.7A$	23	32	nC
Q _{gs}	Gate to Source Charge	I _D = 10.7A	7		nC
Q _{gd}	Gate to Drain "Miller" Charge		9		nC

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Dioge Forward Voltage	$V_{GS} = 0V, I_{S} = 10.7A$ (Note 2)	0.8	1.3	V
		$V_{GS} = 0V, I_S = 2.6A$ (Note 2)	0.7	1.2	
t _{rr}	Reverse Recovery Time	1 10.74 di/dt 1004/	28	45	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 10.7A$, di/dt = $100A/\mu s$	21	34	nC

¹ R_{9JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BJA} is determined by the user's board design.



a) 40°C/W when mounted on a 1 in² pad of 2 oz copper



b) 96°C/W when mounted on a minimum pad.

- 2: Pulse Test: Pulse Width < 300μ s, Duty cycle < 2.0%. 3: E_{AS} of 253mJ is based on starting T_J = 25° C, L = 3mH, I_{AS} = 13A, V_{DD} = 60V, V_{GS} = 10V. 100% test at L = 0.1mH, I_{AS} = 41A.

Typical Characteristics T_J = 25°C unless otherwise noted

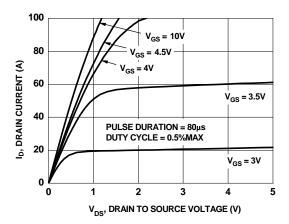


Figure 1. On-Region Characteristics

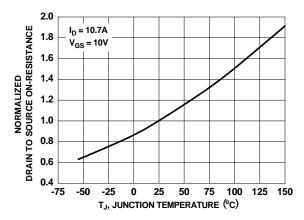


Figure 3. Normalized On-Resistance vs Junction Temperature

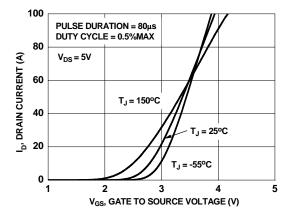


Figure 5. Transfer Characteristics

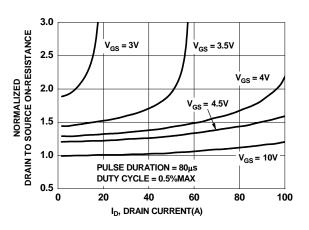


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

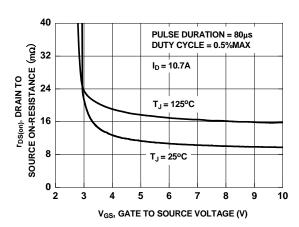


Figure 4. On-Resistance vs Gate to Source Voltage

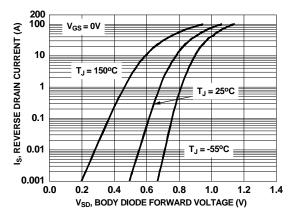


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

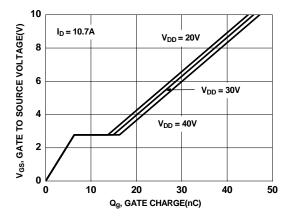


Figure 7. Gate Charge Characteristics

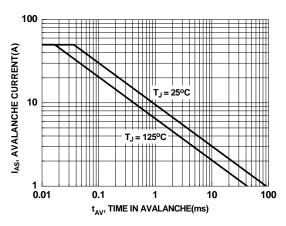


Figure 9. Unclamped Inductive Switching Capability

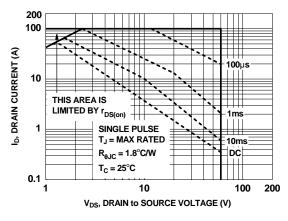


Figure 11. Forward Bias Safe Operating Area

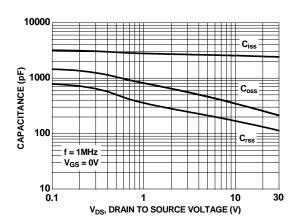


Figure 8. Capacitance vs Drain to Source Voltage

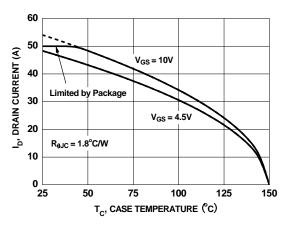


Figure 10. Maximum Continuous Drain Current vs Case Temperature

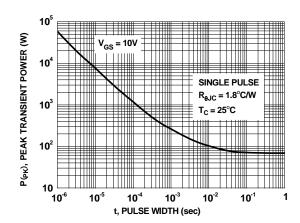


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

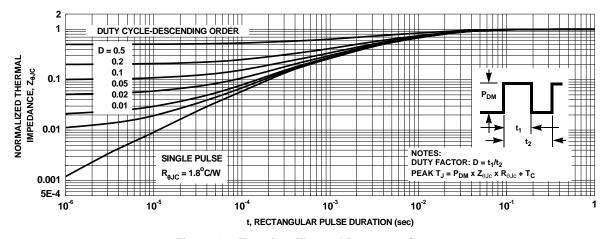


Figure 13. Transient Thermal Response Curve

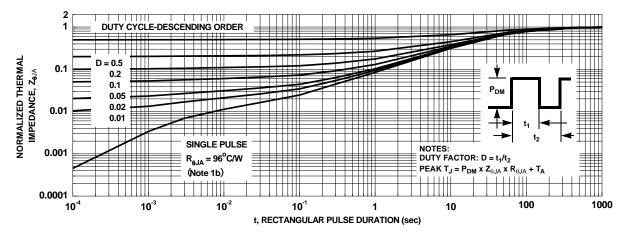
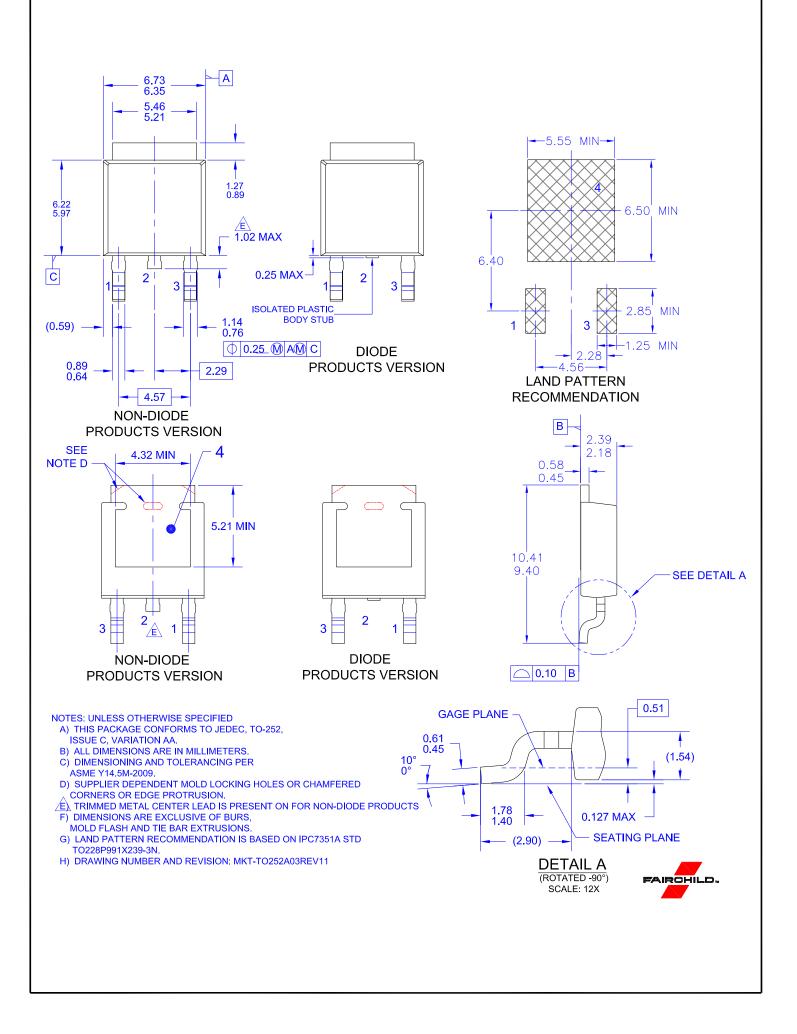


Figure 14. Transient Thermal Response Curve



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